



# SISPAD 2007

International Conference on  
Simulation of Semiconductor Processes and Devices

## Call for Papers

The 12<sup>th</sup> International Conference on Simulation of Semiconductor Devices and Processes (SISPAD) will be held from September 25-27, 2007 at the TU Wien, Vienna, Austria. Following the tradition of the SISPAD conference series as the leading forum for Technology Computer-Aided Design (TCAD), this conference provides an opportunity for the presentation and discussion of recent advances in modeling and simulation of semiconductor devices, processes and equipment. The scientific program consists of invited and contributed presentations and a poster session.



### Conference Chairmen

T. Grasser, Austria  
S. Selberherr, Austria

### Technical Program Committee

V. Axelrad, USA  
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T. Grasser, Austria  
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### General Topic Areas

Device simulation, including transport in nano-structures  
Models of VLSI device scaling limits, quantum effects, and novel devices  
Process simulation, including both continuum and atomistic approaches  
Equipment, topography, and lithography simulation  
Interconnect modeling and algorithms including noise and parasitic effects  
Compact device modeling for circuit simulation  
Integration of circuit and device simulation  
User interfaces and visualization  
High performance computing, numerical methods and algorithms  
Mesh generation and adaptation  
Simulation of devices like microsensors and optoelectronic devices  
Benchmarking, calibration, and verification of simulators

### Abstracts and Proceedings

A two page abstract should be uploaded to the conference homepage. Postal submission of hardcopies is not acceptable. Authors of accepted papers are request to submit a four page final paper which will be published in the conference proceedings. Additional information for authors is available on the webpage [www.sispad.org](http://www.sispad.org)

### Important Dates

Abstract submission:	March 2, 2007
Notification of acceptance:	May 4, 2007
Camera ready copy:	May 25, 2007
Conference:	September 25-27, 2007

### Venue

The conference will be held in the Electrical Engineering building of the TU Wien: Gusshausstrasse 27-29, A-1040 Vienna, Austria

**September 25-27, 2007 • Vienna**

<http://www.sispad.org>

